

Abstract: (FIG. 1)

**"SUBSTRATE PROCESSING APPARATUS AND SUBSTRATE
PROCESSING METHOD"**

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Thermal processing unit sections each with ten tiers and coating processing unit sections each with five tiers are disposed around a first main wafer transfer section and a second main wafer transfer section, and in the thermal processing unit section, the influence of the time required for substrate temperature regulation processing on a drop in throughput can be reduced greatly by transferring the wafer W while the temperature of the wafer W is being regulated by a temperature regulation and transfer device.

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